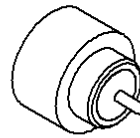
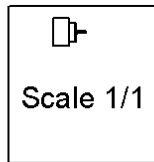
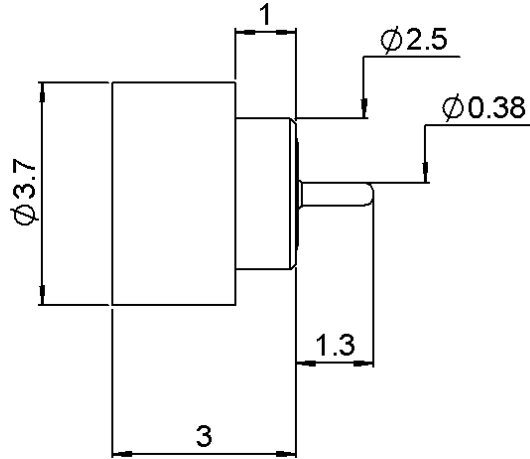


**HERMETIC STRAIGHT MALE RECEPTACLE**  
**SOLDER TYPE - SMOOTH BORE**

**R222.645.720**

Series : SMP



All dimensions are in mm.



COMPONENTS	MATERIALS	PLATINGS ( $\mu\text{m}$ )
BODY	DILVER P1	GOLD 0.5 OVER NICKEL 2
CENTER CONTACT	DILVER P1	GOLD 0.5 OVER NICKEL 2
OUTER CONTACT		
INSULATOR	GLASS	
GASKET		
OTHERS PARTS		
-	-	-
-	-	-

Issue : 0529 B

In the effort to improve our products, we reserve the right to make changes judged to be necessary.



**HERMETIC STRAIGHT MALE RECEPTACLE**

**R222.645.720**

**SOLDER TYPE - SMOOTH BORE**

Series : SMP

**PACKAGING**

**SPECIFICATION**

Standard	Unit	Other
<b>100</b>	<b>'W' option</b>	<b>Contact us</b>

**ELECTRICAL CHARACTERISTICS**

**ENVIRONMENTAL**

Impedance		<b>50</b> Ω
Frequency		<b>0-18</b> GHz
VSWR	<b>1.15</b> +	<b>0.000</b> x F(GHz) Maxi
Insertion loss		<b>0.12</b> √F(GHz) dB Maxi
RF leakage	- (	- F(GHz)) dB Maxi
Voltage rating		<b>335</b> Veff Maxi
Dielectric withstanding voltage		<b>500</b> Veff mini
Insulation resistance		<b>5000</b> MΩ mini

Operating temperature	<b>-65/+165</b> ° C
Hermetic seal	<b>10-8</b> Atm.cm3/s
Panel leakage	<b>NA</b>

**OTHERS CHARACTERISTICS**

Assembly instruction

Others :

**MECHANICAL CHARACTERISTICS**

Center contact retention		
Axial force – Mating end	<b>6.8</b>	N mini
Axial force – Opposite end	<b>6.8</b>	N mini
Torque	<b>NA</b>	N.cm mini
Recommended torque		
Mating	<b>NA</b>	N.cm
Panel nut	<b>NA</b>	N.cm
Mating life	<b>1000</b>	Cycles mini
Weight	<b>0.085</b>	g

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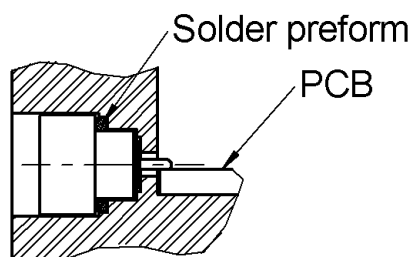


**HERMETIC STRAIGHT MALE RECEPTACLE**

**R222.645.720**

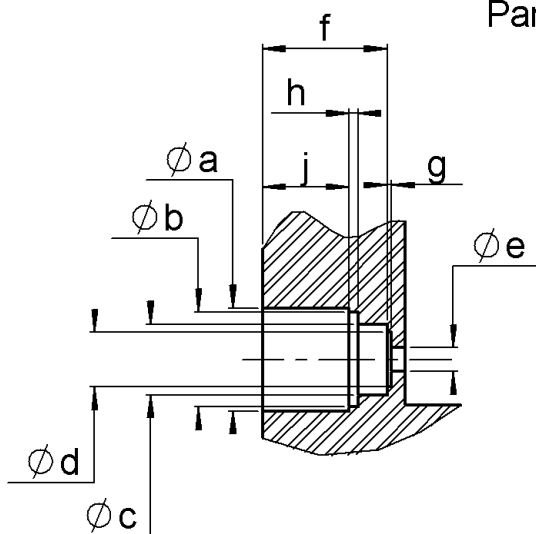
**SOLDER TYPE - SMOOTH BORE**

Series : SMP



1. Degrease and clean connector and box
2. Solder the connector on the panel  
we advise SnAg4 Cu0.5, we recommend a low residue flux.  
Preheating at 100 °C. Take care not to exceed 260°C during solder operation
3. Solder the pin on the track  
we advise SnAg4 Cu0.5, we recommend a low residue flux.  
Preheating at 100 °C (only for ceramic substrate). Take care not to exceed 260°C during solder operation

Panel mounting hole



a	3,76 - 3,78
b	3,43 - 3,55
c	2,59 - 2,61
d	1,95 - 2,05
e	0,87 - 0,91
f	4,04 - 4,09
g	0,13 - 0,17
h	0,28 - 0,38
j	3,15 - 3,19

Issue : 0529 B

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